



#510  
9/24/02

PATENT

Customer No. 22,852

Attorney Docket No. 04329.2567

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yasuhiro YAMAJI

Application No.: 09/871,671

Filed: June 4, 2001

For: SEMICONDUCTOR DEVICE  
USING SUBSTRATE HAVING  
CUBIC STRUCTURE AND  
METHOD OF MANUFACTURING  
THE SAME

)  
)  
) Group Art Unit: 2827

)  
) Examiner: J. Mitchell

*Smith*

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Commissioner for Patents  
Washington, DC 20231

Sir:

**AMENDMENT**

In reply to the Office Action dated June 19, 2002, please amend the application as follows:

**IN THE CLAIMS:**

Please cancel claim 24 without prejudice or disclaimer of the subject matter thereof, amend claims 1-10, 12-23, and 26, and rewrite claim 25, as follows:

1. (Amended) A semiconductor device, comprising:

a cylindrical substrate having wirings formed thereon; and

at least one semiconductor chip mounted on a circumferential surface of said

substrate, said semiconductor chip being bent along the surface of said substrate and having bumps in contact with the wirings.

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